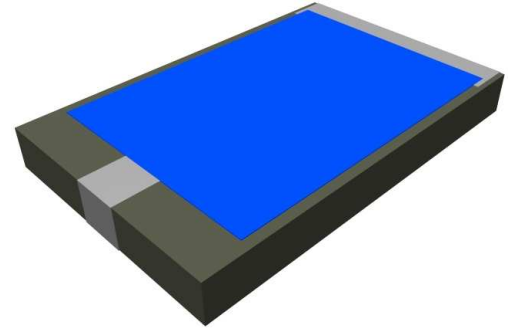


FEATURES

Optimized For Cellular Spectrum
Low VSWR
100% Tested

APPLICATIONS

Mobile Networks
Broadcast
High Power Amplifiers
Instrumentation
Isolators
Satellite Communications



GENERAL DESCRIPTION

EMC Technology's surface mount terminations are designed for direct installation on printed circuit boards and manufactured using thick film technology. Edge metallization on two sides form the solder fillets for stronger attachment, easier inspection and increased heat removal area. The devices are available in Alumina, Aluminum Nitride or Beryllium Oxide.

SPECIFICATIONS

1.0 ELECTRICAL

Nominal Impedance: 50 Ω
Frequency Range: 800 MHz – 2700 MHz
VSWR: 1.15:1 Max
Temperature Coefficient: ± 200 PPM/ $^{\circ}$ C Max
Power Rating: 100 Watts
Operating Temperature: -55 $^{\circ}$ C To +150 $^{\circ}$ C
DC Resistance: 45.6 $\Omega \pm 5\%$

2.0 MECHANICAL

Substrate: AlN
Resistive Film: Thick Film
Metallization: Thick Film

3.0 UNIT MARKING

None

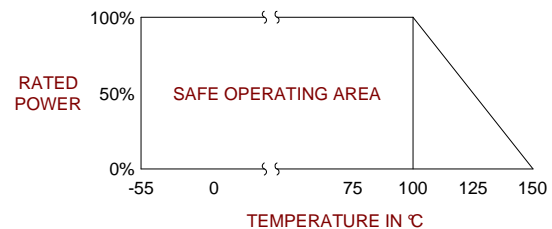
4.0 PACKAGING

Standard: Tape and Reel

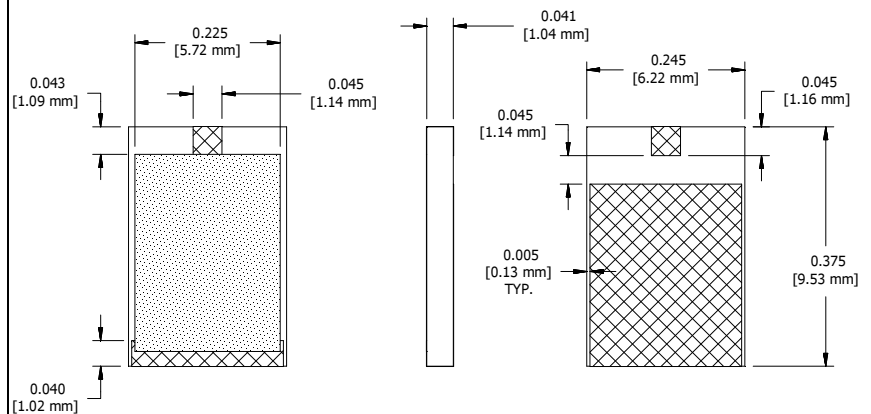
5.0 PART NUMBERING

Part Identifier: SMT3725TALNF

POWER RATING AND DERATING



MECHANICAL OUTLINE



Note: Specifications are subject to change without notice.

TOLERANCE: $\pm .010$